

NCE20N65,NCE20N65F

Pb-Free Product

Super Junction MOSFET

NCE N-Channel Enhancement Mode Power MOSFET

General Description

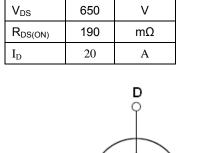
The series of devices use advanced super junction technology and design to provide excellent RDS(ON) with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

Features

- New technology for high voltage device
- Low on-resistance and low conduction losses
- ●small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)



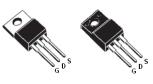
Schematic diagram

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Package Marking And Ordering Information

Device	Device Package	Marking
NCE20N65	TO-220	NCE20N65
NCE20N65F	TO-220F	INCE201005



TO-220 TO-220F

Table 1. Absolute Maximum Ratings ($T_c=25^{\circ}$)

Parameter	Symbol	NCE20N65	NCE20N65F	Unit
Drain-Source Voltage (VGs=0V)	VDS	6	50	V
Gate-Source Voltage (VDs=0V)	Vgs	±	30	V
Continuous Drain Current at Tc=25°C	I _{D (DC)}	20	20*	А
Continuous Drain Current at Tc=100°C	I _{D (DC)}	12.5	12.5*	А
Pulsed drain current (Note 1)	DM (pluse)	60	60*	А
Drain Source voltage slope, VDS = 480 V, ID = 20 A, Tj =	dv/dt	50		V/ns
125 °C	uv/ut		50	V/115
Maximum Power Dissipation(Tc=25°C)	PD	208	34.5	W
Derate above 25°C		1.67	0.28	W/°C
Single pulse avalanche energy (Note 2)	Eas	690		mJ
Avalanche current ^(Note 1)	I _{AR}	2	20	А



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Repetitive Avalanche energy , t_{AR} limited by T_{jmax} (Note 1)	E _{AR}	1	mJ
Operating Junction and Storage Temperature Range	T_{J},T_{STG}	-55+150	°C

* limited by maximum junction temperature

Table 2. Thermal Characteristic

Parameter	Symbol	NCE20N65	NCE20N65F	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R _{thJC}	0.6	3.6	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R _{thJA}	62	80	°C /W

Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	650			V
Zero Gate Voltage Drain Current(Tc=25℃)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			1	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			100	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±30V,V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	2.5	3	3.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =10A			190	mΩ
Dynamic Characteristics						
Forward Transconductance	g fs	V _{DS} = 20V, I _D = 10A		17.5		S
Input Capacitance	Clss			2300		PF
Output Capacitance	Coss	- V _{DS} =100V,V _{GS} =0V, F=1.0MHz		95		PF
Reverse Transfer Capacitance	C _{rss}			7		PF
Total Gate Charge	Qg	V = 490V(1 = 20A		85	114	nC
Gate-Source Charge	Q _{gs}	V _{DS} =480V,I _D =20A, V _{GS} =10V		11		nC
Gate-Drain Charge	Q_gd	V _{GS} -10V		33		nC
Switching times						
Turn-on Delay Time	t _{d(on)}			10		nS
Turn-on Rise Time	tr	V _{DD} =380V,I _D =20A,		5		nS
Turn-Off Delay Time	t _{d(off)}	R _G =3.6Ω,V _{GS} =10V		67	100	nS
Turn-Off Fall Time	t _f			4	12	nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I _{SD}	T -25°C			20	А
Pulsed Source-drain current(Body Diode)	I _{SDM}	T _C =25°C			60	А
Forward on voltage	V _{SD}	Tj=25°C,I _{SD} =20A,V _{GS} =0V		0.9	1.3	V
Reverse Recovery Time	trr	Ti-25°C L-204 di/dt-1004/wa		500		nS
Reverse Recovery Charge	Q _{rr}	− Tj=25°C,I _F =20A,di/dt=100A/μs		11		nC

Notes 1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25°C,VDD=50V,VG=10V, R_G=25 Ω



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

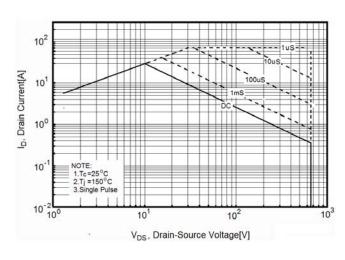


Figure1. Safe operating area for NCE20N65

Figure2. Safe operating area for NCE20N65F

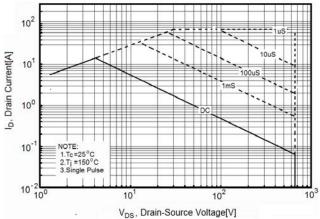


Figure3. Source-Drain Diode Forward Voltage

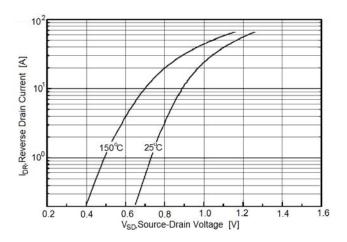


Figure 5. Transfer characteristics

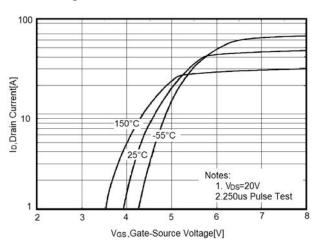


Figure4. Output characteristics

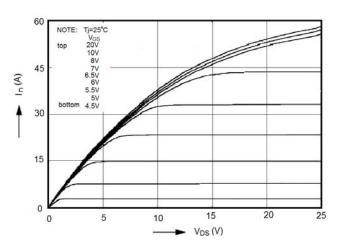


Figure6. Static drain-source on resistance

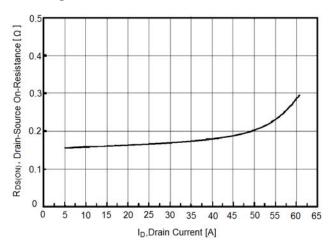




Figure8. BV_{DSS} vs Junction Temperature

0.6 $R_{DS(ON)}$, Drain - Source On - Resistance[Ω] 0.5 0.4 0.3 0.2 0.1 0_60 -20 140 180 20 100 60 TJ,Junction Temperature [°C]

Figure7. R_{DS(ON)} vs Junction Temperature

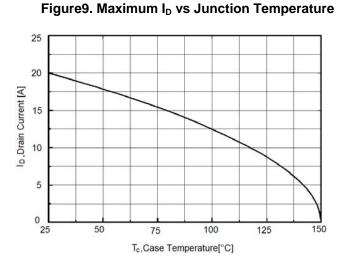


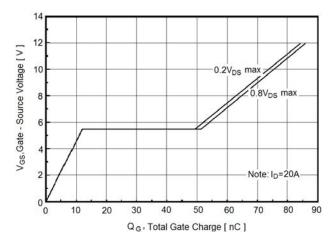
Figure10. Gate charge waveforms

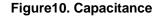
50

100

150

200





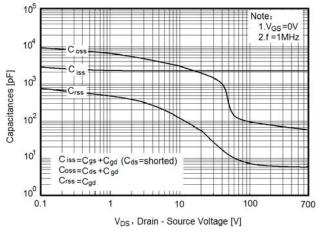
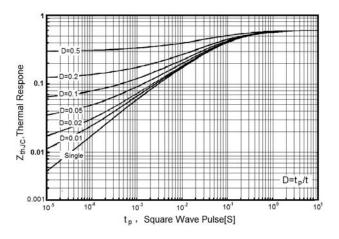


Figure11. Transient Thermal Impedance for NCE20N65



0.8 -100 -50 0 TJ,Junction Temperature [°C]

1.2

1.1

1.0

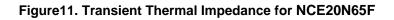
0.9

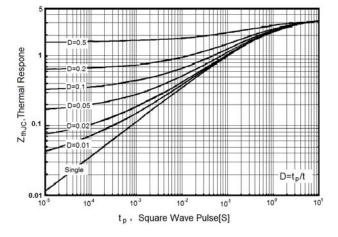
BV _{DSS} (Normalized) , Drain - Source Breakdown Voltage

Vgs =0V

ID=250uA



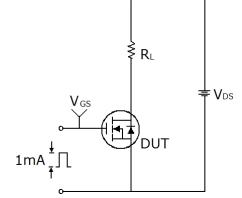




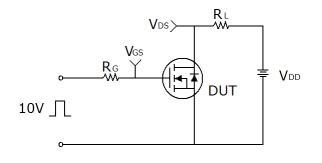


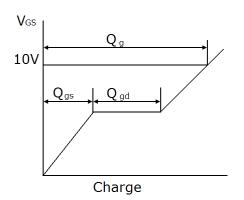
Test circuit

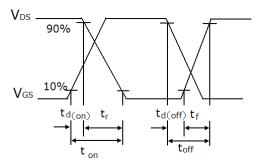
1) Gate charge test circuit & Waveform



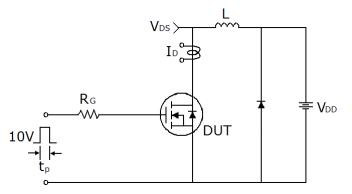
2) Switch Time Test Circuit:

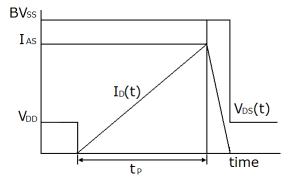






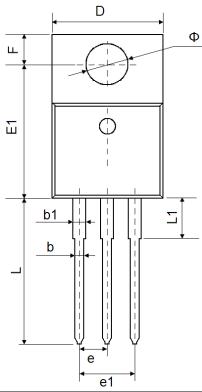
3) Unclamped Inductive Switching Test Circuit & Waveforms

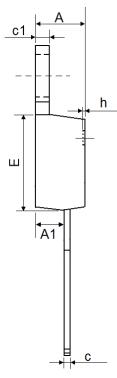


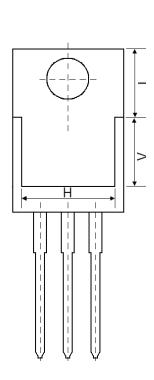




TO-220-3L Package Information



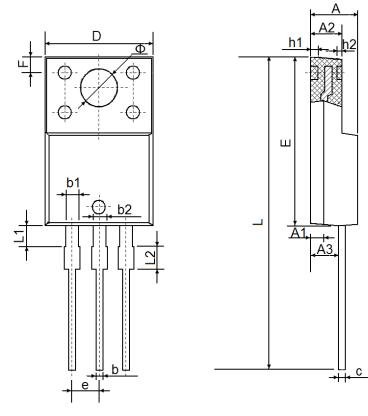




Symbol –	Dimensions	In Millimeters	Dimensions In Inches	
	Min.	Max.	Min.	Max.
	4.470	4.670	0.176	0.184
A1	2.520	2.820	0.099	0.111
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
С	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	10.010	10.350	0.394	0.407
E	8.500	8.900	0.335	0.350
E1	12.060	12.460	0.475	0.491
е	2.54	0 TYP.	0.100 TYP.	
e1	4.980	5.180	0.196	0.204
F	2.590	2.890	0.102	0.114
Н	8.44	0 REF.	0.332 REF.	
h	0.000	0.300	0.000	0.012
L	13.400	13.800	0.528	0.543
L1	3.560	3.960	0.140	0.156
V	6.060 REF.		0.239	REF.
I	6.60	6.600 REF.) REF.
Φ	3.735	3.935	0.147	0.155



TO-220F Package Information



Symbol -	Dimensions	In Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	4.300	4.700	0.169	0.185	
A1	1.30	0REF	0.051REF		
A2	2.800	3.200	0.110	0.126	
A3	2.500	2.900	0.098	0.114	
b	0.500	0.750	0.020	0.030	
b1	1.100	1.350	0.043	0.053	
b2	1.500	1.750	0.059	0.069	
С	0.500	0.750	0.020	0.030	
D	9.960	10.360	0.392	0.408	
E	14.800	15.200	0.583	0.598	
е	2.540)TYP.	0.100TYP		
F	2.70	OREF	0.106REF		
Ф	3.50	OREF	0.138REF		
h1	0.80	OREF	0.031REF		
h2	0.500REF		0.020REF		
L	28.000	28.400	1.102	1.118	
L1	1.700	1.900	0.067	0.075	
L2	1.900	2.100	0.075	0.083	



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